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R216CH16

- Power Thyristor

1600 V_{DRM};

Features:

- . All Diffused Structure
- . Interdigitated Amplifying Gate Configuration
- . Blocking capabilty up to 1600 volts
- . Guaranteed Maximum Turn-Off Time
- . High dV/dt Capability
- . Pressure Assembled Device



ELECTRICAL CHARACTERISTICS AND RATINGS

Blocking - Off State

Device Type	V _{RRM} (1)	V _{DRM} (1)	V _{RSM} (1)
R216CH	1600	1600	1700

 V_{RRM} = Repetitive peak reverse voltage

 V_{DRM} = Repetitive peak off state voltage

 V_{RSM} = Non repetitive peak reverse voltage (2)

Repetitive peak reverse leakage and off state leakage	$I_{RRM/}I_{DRM}$	50 mA 50 mA (3)
Critical rate of voltage rise	dV/dt (4)	500 V/μsec

Conducting - on state

Notes:

All ratings are specified for Tj=25 °C unless otherwise stated.

- (1) All voltage ratings are specified for an applied 50Hz/60zHz sinusoidal waveform over the temperature range -40 to +125 °C.
- (2) 10 msec. max. pulse width
- (3) Maximum value for Tj = 125 °C.
- (4) Minimum value for linear and exponential waveshape to 80% rated V_{DRM} . Gate open. Tj = 125 °C.
- (5) Non-repetitive value.
- (6) The value of di/dt is established in accordance with EIA/NIMA Standard RS-397, Section 5-2-2-6. The value defined would be in addition to that obtained from a snubber circuit, comprising a 0.2 μF capacitor and 20 ohms resistance in parallel with the thristor under test.

Parameter	Symbol	Min.	Max.	Тур.	Units	Conditions
Average value of on-state	I_{TAV}		633		A	Sinewave,180° conduction,T _s =55°C
current						
Peak one cPSTCle surge						10.0 msec (50Hz), sinusoidal wave-
(non repetitive) current	I_{TSM}		6900		Α	shape, 180° conduction, $T_j = 125 {}^{\circ}\text{C}$
I square t	I^2t		2.40×10^6		A^2s	10.0 msec
Latching current	I_{L}		1000		mA	$V_D = 24 \text{ V}; R_L = 12 \text{ ohms}$
Holding current	I_{H}		500		mA	$V_{D} = 24 \text{ V}; I = 2.5 \text{ A}$
Peak on-state voltage	V_{TM}		1.90		V	$I_{TM} = 1000 \text{ A}$; Duty cPSTCle $\leq 0.01\%$ $T_j = 125 ^{\circ}\text{C}$
Critical rate of rise of on-state current (5, 6)	di/dt		200		A/µs	Switching from V _{DRM} ≤ 1000 V, non-repetitive
Critical rate of rise of on-state current (6)	di/dt		100		A/μs	Switching from V _{DRM} ≤ 1000 V

Gating

Parameter	Symbol	Min.	Max.	Тур.	Units	Conditions
Peak gate power dissipation	P_{GM}		200	J1	W	$t_p = 40 \text{ us}$
Average gate power dissipation	P _{G(AV)}		5		W	
Peak gate current	I_{GM}		10		A	
Gate current required to trigger all	I_{GT}		300		mA	$V_D = 6 \text{ V}; R_L = 3 \text{ ohms}; T_i = -40 ^{\circ}\text{C}$
units			150		mA	$V_D = 6 \text{ V}; R_L = 3 \text{ ohms}; T_j = +25 \text{ °C}$
			125		mA	$V_D = 6 \text{ V}; R_L = 3 \text{ ohms}; T_i = +125^{\circ} \text{C}$
Gate voltage required to trigger all	V_{GT}		5		V	$V_D = 6 \text{ V;} R_L = 3 \text{ ohms;} T_j = -40 \text{ °C}$
units			3		V	$V_D = 6 \text{ V}; R_L = 3 \text{ ohms}; T_j = 0-125^{\circ}\text{C}$
		0.30			V	$V_D = Rated V_{DRM}$; $R_L = 1000 ohms$;
						$T_{i} = + 125 {}^{\circ}\text{C}$
Peak negative voltage	V_{GRM}		5		V	

Dynamic

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Delay time	t _d		1.5	0.7	μs	$I_{TM} = 50 \text{ A}; V_D = \text{Rated } V_{DRM}$
						Gate pulse: $V_G = 20 \text{ V}$; $R_G = 20 \text{ ohms}$;
						$t_r = 0.1 \ \mu s; \ t_p = 20 \ \mu s$
Turn-off time (with $V_R = -50 \text{ V}$)	t_q	20	30		μs	$I_{TM} = 550 \text{ A}; \text{ di/dt} = 40 \text{ A/}\mu\text{s};$
						$V_R \ge -50 \text{ V}$; Re-applied dV/dt = 20
						$V/\mu s$ linear to 80% V_{DRM} ; $V_G = 0$;
						$T_i = 125$ °C; Duty cPSTCle $\ge 0.01\%$
Reverse recovery charge	Q _{rr}		*	200	μС	$I_{TM} = 550 \text{ A}; \text{ di/dt} = 40 \text{ A/}\mu\text{s};$
						$V_R \ge -50 \text{ V}$

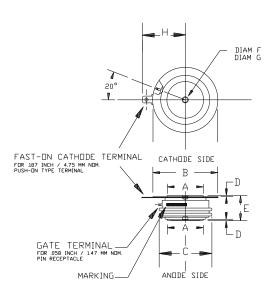
^{*} For guaranteed max. value, contact factory.

THERMAL AND MECHANICAL CHARACTERISTICS AND RATINGS

Parameter	Symbol	Min.	Max.	Тур.	Units	Conditions
Operating temperature	T _j	-40	+125		°C	
Storage temperature	T_{stg}	-40	+150		°C	
Thermal resistance - junction to case	R _e (j-c)	0.045 0.090	0.055 0.110		°C/W	Double sided cooled Single sided cooled
Thermal resistance - case to sink	R _{e (c-s)}		0.030 0.060		°C/W	Double sided cooled * Single sided cooled *
Mounting force	P	800 3.6	2500 11.1		lb. kN	
Weight	W			2.5 70	oz. g	

^{*} Mounting surfaces smooth, flat and greased

Note: for case outline and dimensions, see case outline drawing in page 4 of this Technical Data



STRIKE DISTANCE = .23 INCH / 5.8 MM MIN. CREEPAGE DISTANCE = .40 INCH / 10.2 MM MIN.

DUTLINE DIMENSIONS - CASE 2T								
DIMENSIONS	ENSIONS Min.		Min. In.	Max. In.				
DIAM A DIAM B DIAM C D E F G H	24.89 40.64 0.76 13.72 3.30 1.78 27.69	25.40 42.16 40.39 15.24 3.81 2.03 28.70	0.98 1.60 0.03 0.54 0.13 0.07 1.09	1.00 1.65 1.59 0.60 0.15 0.08 1.13				